

Applic. No.: 10/682,649

Amdt. Dated January 31, 2005

Reply to Office action of November 5, 2004

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

Claim 1 (currently amended). A memory module comprising:

a board having an upper surface;

a memory device attached to ~~the~~ said board, said memory device having a lower surface; and

a heat dissipation means arranged in a gap between said lower surface of said the memory device and said upper surface of said the board;

said heat dissipation means including an area of said board at which solder varnish covering said board is removed; and

said memory device bordering said board in said area.

Claim 2 (currently amended). The memory module of claim 1, wherein ~~the~~ said heat dissipation means includes a heat-conducting paste between ~~the~~ said board ~~10~~ and ~~the~~ said memory device ~~(12)~~.

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Claim 3 (cancelled).

Claim 4 (currently amended). ~~Memory module of claim 1, wherein~~

A memory module, comprising:

a board having an upper surface;

a memory device attached to said board, said memory device

having a lower surface;

a heat dissipation means arranged in a gap between said lower

surface of said memory device and said upper surface of said

board;

the said heat dissipation means ~~includes~~ including a metal

layer; and

said metal layer being connected to a conductive trace.

Claim 5 (currently amended). The memory module of claim 4,
wherein ~~the metal layer~~ said conductive trace ~~is connected to~~
a supply line to which, in operation, a supply potential is
applied.

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Claim 6 (cancelled).

Claim 7 (currently amended). The memory module of claim 6 4, wherein ~~the~~ said conductive trace is meander-shaped.

Claim 8 (currently amended). The memory module of claim 4, wherein ~~the~~ said metal layer includes a heat sink.

Claim 9 (currently amended). The memory module of claim 2, wherein ~~the~~ said heat dissipation means includes a contact hole.

Claim 10 (currently amended). The memory module of claim 9, wherein ~~the~~ said contact hole is connected to a supply line at which, in operation, a supply potential is applied.

Claim 11 (cancelled).

Claim 12 (currently amended). ~~Memory module of claim 1,~~
~~wherein~~ A memory module, comprising:

a board having an edge;

a memory device attached to said board;

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a heat dissipation means arranged between said memory device
and said board;

a frame arranged at said edge of said board and including a
heat-conductive material; and

~~the metal~~ said frame comprises including taps by means of
~~which same can be heat-conductively connected for heat-~~
conductively connecting to a socket or a motherboard.